HMC574AMS8E

v01.0316

GaAs MMIC 5 WATT T/R SWITCH DC - 3 GHz

Typical Applications

The HMC574AMS8E is ideal for:

- Cellular/3G Infrastructure
- Private Mobile Radio Handsets
- WLAN, WiMAX & WiBro
- Automotive Telematics
- Test Equipment

Features

Low Insertion Loss: 0.3 dB

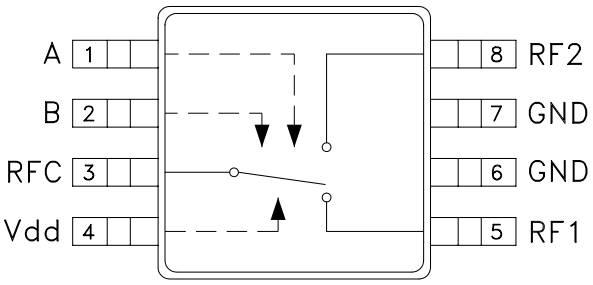
High Third Order Intercept: +63 dBm

Isolation: 30 dB

Single Positive Supply: +3 to +8V

SMT Package: MSOP8

Functional Diagram



General Description

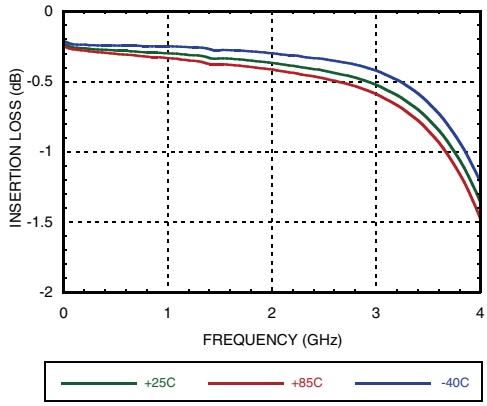
The HMC574AMS8E is low-cost SPDT switch in 8-lead MSOP packages for use in transmit/receive applications which requires very low distortion at high incident power levels. The device can control signals from DC to 3 GHz and is especially suited for Cellular/3G infrastructure, WiMAX and WiBro applications with only 0.3 dB typical insertion loss. The design provides 5 watt power handling performance and +63 dBm third order intercept at +8 Volt bias. RF1 and RF2 are reflective shorts when "Off".

Electrical Specifications, T_A = +25° C, Vctl = 0/+5 Vdc, Vdd = +5 Vdc (Unless Otherwise Stated), 50 Ohm System

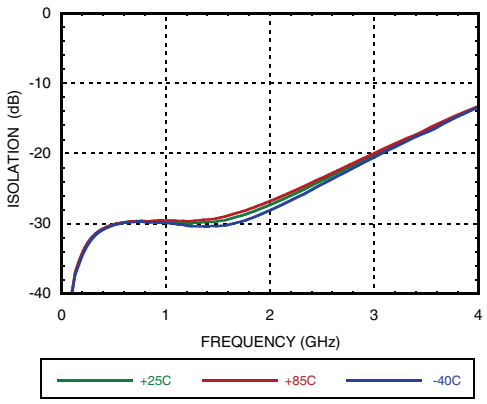
Parameter		Frequency	Min.	Typ.	Max.	Units
Insertion Loss		DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz		0.25 0.3 0.4 0.5	0.5 0.6 0.7 0.8	dB dB dB dB
Isolation		DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz	26 24 21 16	30 28 25 20		dB dB dB dB
Return Loss		DC - 1.0 GHz DC - 2.0 GHz DC - 2.5 GHz DC - 3.0 GHz		35 30 25 22		dB dB dB dB
Input Power for 1dB Compression	Vctl = 0/+3V Vctl = 0/+5V Vctl = 0/+8V	0.5 - 3.0 GHz	31 35 37	34 38 39		dBm dBm dBm
Input Third Order Intercept P_{tone} = Two-tone Input Power (Each Tone)	Vctl = 0/+3V, P_{tone} = +23 dBm Vctl = 0/+5V, P_{tone} = +27 dBm Vctl = 0/+8V, P_{tone} = +27 dBm	0.5 - 3.0 GHz		63 63 63		dBm dBm dBm
Switching Characteristics		DC - 3.0 GHz				
	tRISE, tFALL (10/90% RF)			40		ns
	tON, tOFF (50% CTL to 10/90% RF)			70		ns

For price, delivery, and to place orders: Analog Devices, Inc., One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106
Phone: 781-329-4700 • Order online at www.analog.com
Application Support: Phone: 1-800-ANALOG-D

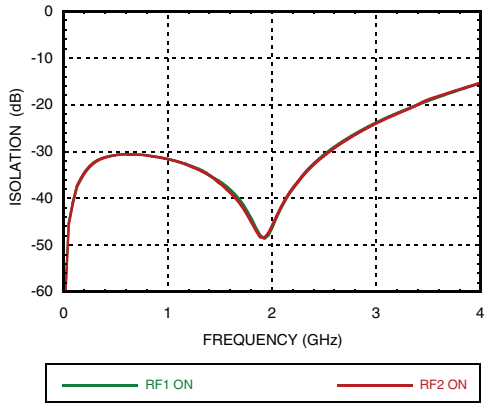
Insertion Loss



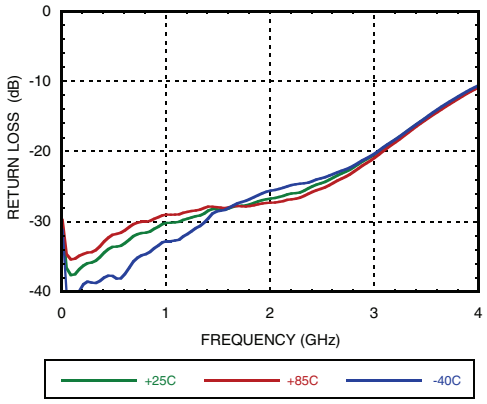
Isolation Between RFC & RF1/RF2



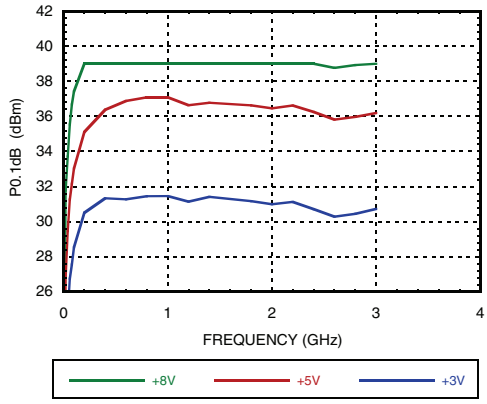
RF1 to RF2 Isolation



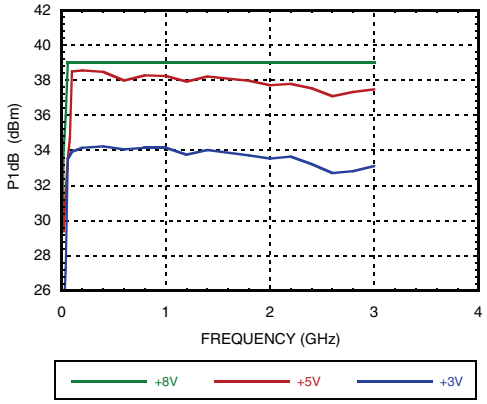
Return Loss



Input P0.1dB vs. Vdd



Input P1dB vs. Vdd



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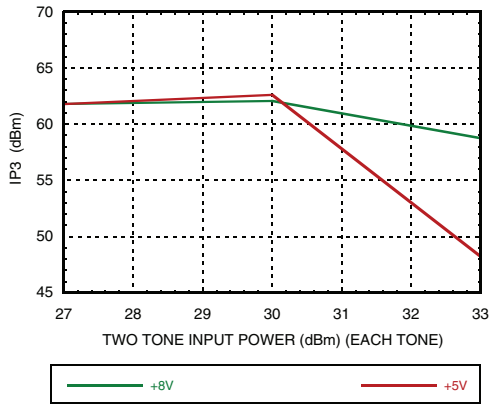
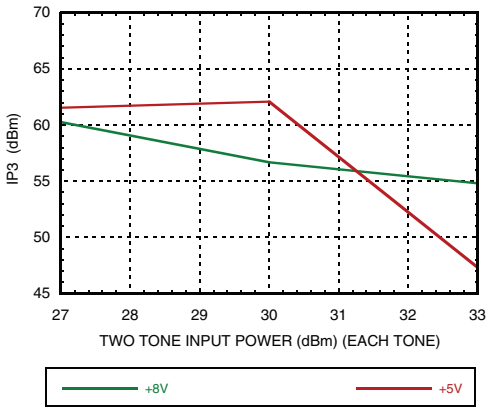
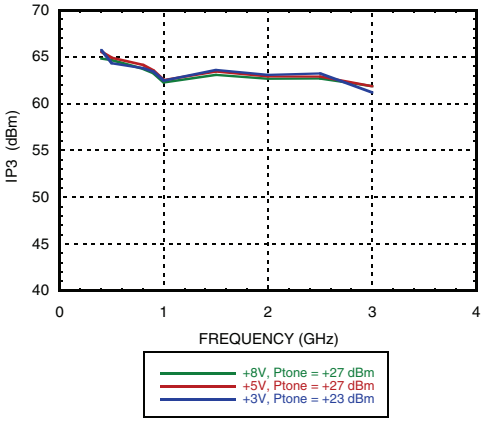
Input IP3 vs. Input Power @ 900 MHz



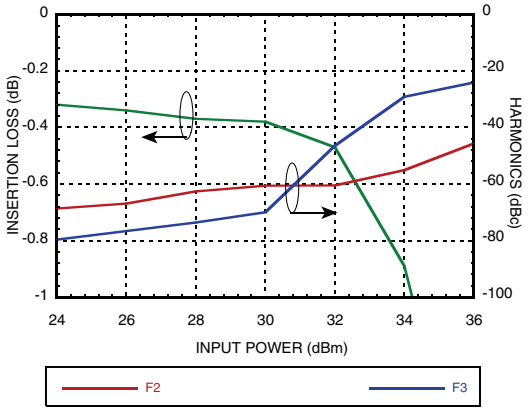
Input IP3 vs. Input Power @ 1900 MHz



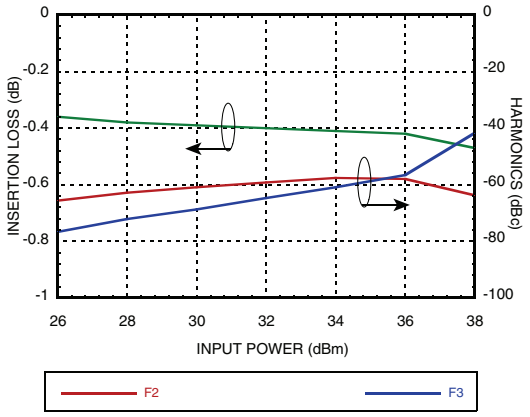
Input Third Order Intercept



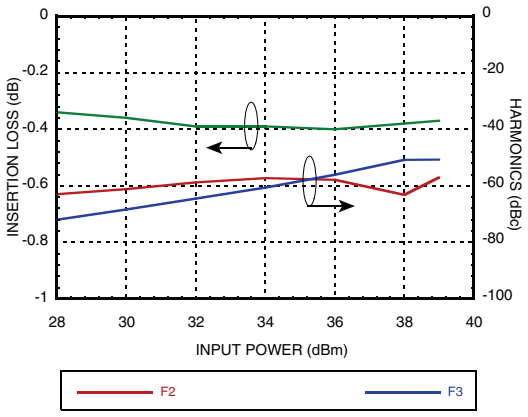
2nd & 3rd Harmonics @ 900 MHz Vdd = +3 Volts



2nd & 3rd Harmonics @ 900 MHz Vdd = +5 Volts



2nd & 3rd Harmonics @ 900 MHz Vdd = +8 Volts



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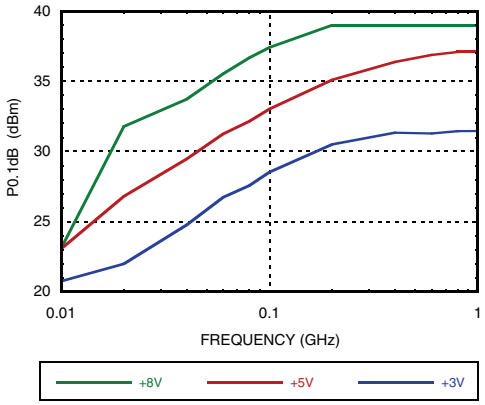
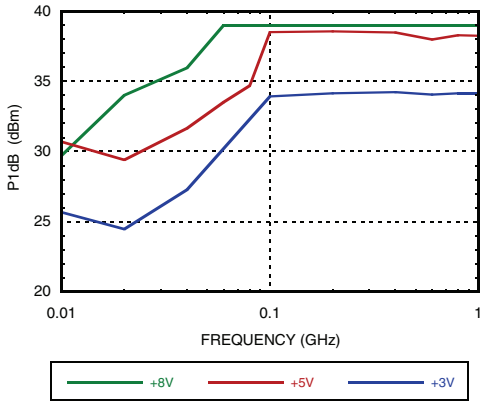
Input P0.1dB vs. Vdd



Input P1dB vs. Vdd



Absolute Maximum Ratings

Max. Input Power V_{dd} = 0/+8V	0.5 - 2.5 GHz	39 dBm
Bias Voltage Range (Vdd)		-0.2 to +10 Vdc
Control Voltage Range (A & B)		-0.2 to +Vdd Vdc
Channel Temperature		150 °C
Continuous Pdiss (T= + 85 °C) (derate 10 mW/°C above 85 °C)		0.775W
Thermal Resistance		83.9 °C/W
Storage Temperature		-65 to +150 °C
Operating Temperature		-40 to +85 °C
ESD Sensitivity (HBM)		Class 1A

DC Blocks are required at ports RFC, RF1 and RF2

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Bias Voltage & Current

Vdd (Vdc)	Typical Idd (µA)
+3	0.5
+5	1
+8	20

Control Voltages

State	Bias Condition
Low	0 to +0.2 Vdc @ 1 µA Typical
High	Vdd ± 0.2 Vdc @ 1 µA Typical

Truth Table

Control Input (Vctl)		Signal Path State	
A	B	RFC to RF1	RFC to RF2
High	Low	Off	On
Low	High	On	Off

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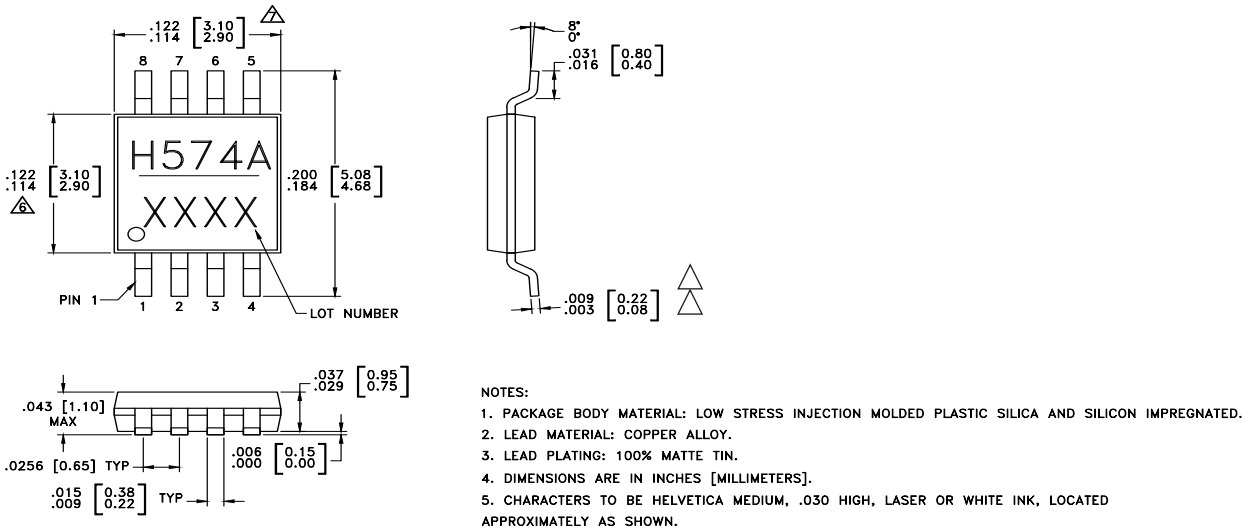
Outline Drawing



NOTES:

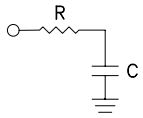
1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD MATERIAL: COPPER ALLOY.
3. LEAD PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. CHARACTERS TO BE HELVETICA MEDIUM, .030 HIGH, LASER OR WHITE INK, LOCATED APPROXIMATELY AS SHOWN.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
7. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
8. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC574AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [1]	H574A XXXX

[1] Max peak reflow temperature of 260 °C
[2] 4-Digit lot number XXXX

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	A	See truth table and control voltage table.	
2	B	See truth table and control voltage table.	
3, 5, 8	RFC, RF1, RF2	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required.	
4	Vdd	Supply Voltage.	
6, 7	GND	This pin must be connected to RF/DC ground.